

Dual N-Channel Enhancement Mode Power MOSFET

DESCRIPTION

The HM680I uses advanced trench technology to provide excellent $R_{\rm DS(ON)}$, low gate charge and operation with gate voltages as low as 2.5V. This device is suitable for use as a Battery protection or in other Switching application.

GENERAL FEATURES

• $V_{DS} = 20V, I_D = H \stackrel{\triangleright}{E} A$

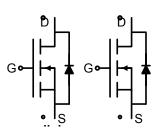
 $R_{DS(ON)} < 59m\Omega$ @ V_{GS} =2.5V

 $R_{DS(ON)}$ < 45m Ω @ V_{GS} =4.5V

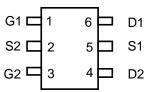
- High Power and current handing capability
- Lead free product is acquired
- Surface Mount Package

Application

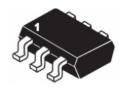
- PWM applications
- Load switch
- ●Power management



Schematic diagram



Marking and pin Assignment



SOT23-6L top view

Package Marking And Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
6800M	HM680I	SOT-23-6L	Ø180mm	8 mm	3000 units

Absolute Maximum Ratings (TA=25℃unless otherwise noted)

Parameter	Symbol	Limit	Unit	
Drain-Source Voltage	V _{DS} 20		V	
Gate-Source Voltage	V _{GS}	±12	V	
Drain Current-Continuous	I _D		ÁA	
Drain Current-Pulsed (Note 1)	I _{DM} A	₩₩₩	Α	
Maximum Power Dissipation	P _D 1.4		W	
Operating Junction and Storage Temperature Range	T_{J} , T_{STG}	-55 To 150	$^{\circ}$	

Thermal Characteristic

Thermal Resistance, Junction-to-Ambient (Note 2)	$R_{\theta JA}$	1.0	°C/W
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Electrical Characteristics (TA=25°C unless otherwise noted)

Parameter	Symbol	Condition	Min	Тур	Max	Unit
Off Characteristics						
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V I _D =250μA	20	33	-	V

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Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =20V,V _{GS} =0V	-	-	1	μA
Gate-Body Leakage Current	I _{GSS}	V _{GS} =±12V,V _{DS} =0V	-	-	±100	nA
On Characteristics (Note 3)						
Gate Threshold Voltage	V _{GS(th)}	V _{DS} =V _{GS} ,I _D =250μA	0.5	0.75	1.2	V
Dunin Course On Ctata Registeres	R _{DS(ON)}	V _{GS} =G5V, I _D =2.Í A	-	37	59	mΩ
Drain-Source On-State Resistance		V _{GS} =I Ě V, I _D =2.9A	-	30	45	mΩ
Forward Transconductance	g FS	V _{DS} =5V,I _D =2.9A	10	-	-	S
Dynamic Characteristics (Note4)						
Input Capacitance	C _{lss}	\/ -15\/\/ -0\/	-	623	-	PF
Output Capacitance	Coss	V_{DS} =15V, V_{GS} =0V, F=1.0MHz	-	99	-	PF
Reverse Transfer Capacitance	C _{rss}	F=1.0lvinz	-	77	-	PF
Switching Characteristics (Note 4)						
Turn-on Delay Time	t _{d(on)}		-	3.3	-	nS
Turn-on Rise Time	t _r	V _{DD} =15V,I _D =2.9A	-	4.8	-	nS
Turn-Off Delay Time	t _{d(off)}	V_{GS} =10V, R_{GEN} =3 Ω	-	26	-	nS
Turn-Off Fall Time	t _f		-	4	-	nS
Total Gate Charge	Qg	\/ -45\/ - 	-	9.5	-	nC
Gate-Source Charge	Q _{gs}	V _{DS} =15V,I _D =H È A,	-	1.5	-	nC
Gate-Drain Charge	Q_{gd}	- V _{GS} =4.5V	-	3	-	nC
Drain-Source Diode Characteristics						
Diode Forward Voltage (Note 3)	V _{SD}	V _{GS} =0V,I _S =2.9A	-	0.75	1.2	V
Diode Forward Current (Note 2)	I _S		-	-	2.9	Α

Notes:

- 1. Repetitive Rating: Pulse width limited by maximum junction temperature.
- 2. Surface Mounted on FR4 Board, t ≤ 10 sec.
- 3. Pulse Test: Pulse Width ≤ 300µs, Duty Cycle ≤ 2%.
- 4. Guaranteed by design, not subject to production

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

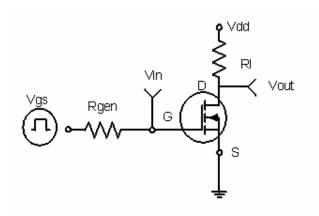


Figure 1:Switching Test Circuit

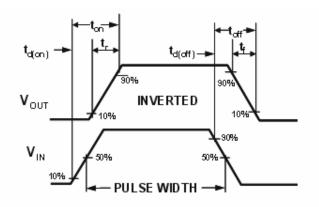
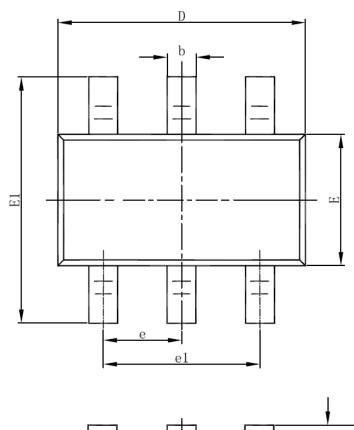
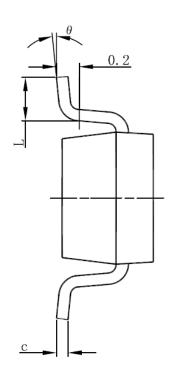
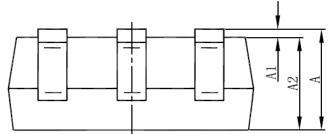


Figure 2:Switching Waveforms

SOT-23-6L PACKAGE OUTLINE DIMENSIONS







Symbol	Dimensions Ir	n Millimeters	Dimensions In Inches		
Symbol	Min	Max	Min	Max	
Α	1.050	1.250	0.041	0.049	
A1	0.000	0.100	0.000	0.004	
A2	1.050	1.150	0.041	0.045	
b	0.300	0.500	0.012	0.020	
С	0.100	0.200	0.004	0.008	
D	2.820	3.020	0.111	0.119	
E	1.500	1.700	0.059	0.067	
E1	2.650	2.950	0.104	0.116	
е	0.950	(BSC)	0.037	(BSC)	
e1	1.800	2.000	0.071	0.079	
L	0.300	0.600	0.012	0.024	
θ	0°	8°	0°	8°	

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